

## 1.5 Amp Negative Adjustable Regulator

### Description

The SGR137/SGR137A is fit, form and function compatible to the SG137/SG137A with the addition of guaranteed performance after radiation exposure to Total Ionizing Dose (TID), Enhanced Low Dose Rate Sensitivity (ELDRS), and Single Event Latch-up (SEL) conditions. The SGR137A family of negative adjustable regulators deliver up to 1.5A output current over an output voltage range of -1.2V to -37V. The device includes significant improvements, such as better line and load regulation, and a maximum output voltage error of 1%. The SGR137 family uses the same chip design and guarantees maximum output voltage error of  $\pm 2\%$ .

Every effort is made to make these devices easy to use and difficult to damage. Internal current and power limiting coupled with true thermal limiting prevents device damage due to overloads or shorts even if the regulator is not fastened to a heat sink.

The SGR137/SGR137A family of products are ideal complements to the SGR117A/117 adjustable positive voltage regulators.

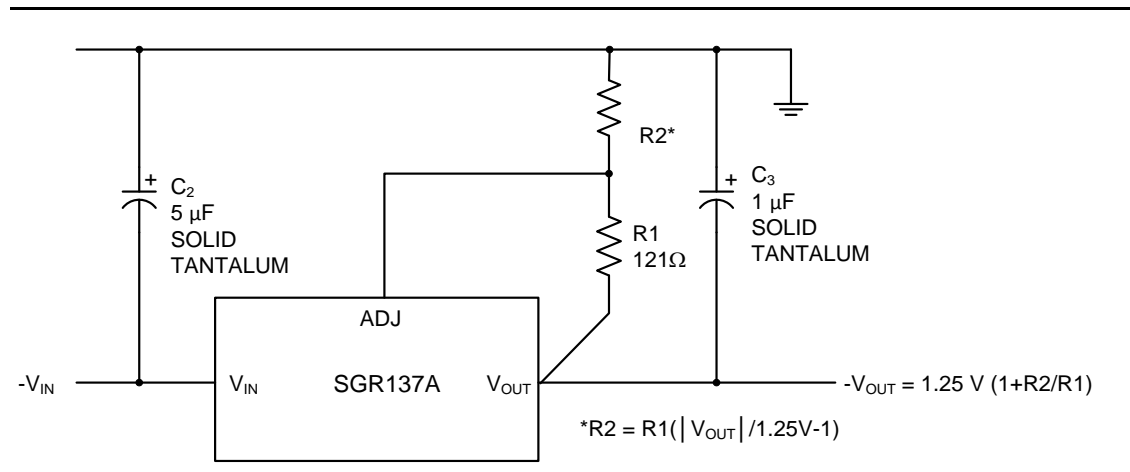
### Features

- 1% Output Voltage Tolerance
- 0.01%/V Line Regulation
- 0.5% Load Regulation
- 0.02%/W Thermal Regulation
- Available in Hermetic TO-220

### High Reliability Features - SGR137/SGR137A

- Rad-tolerance:(Test data available)
- TID to a Minimum of 50krad(Si)
- ELDRS to a Minimum of 50krad(Si)
- SEL Immunity to a Minimum of 87MeV-cm<sup>2</sup>/mg

### Typical Application



**Figure 1** - Typical Application

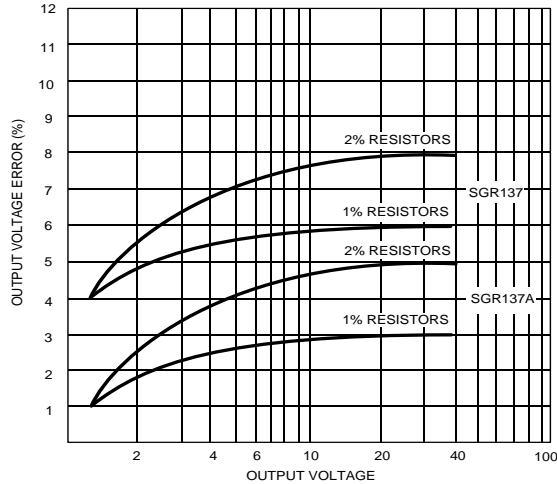


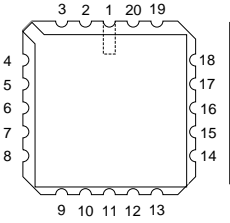
Figure 2 • Resistor Precision vs. Output Voltage Error

## Connection Diagrams and Ordering Information

Ambient Temperature	Type	Package	Part Number	Packaging Type	Connection Diagram
-55°C to 125°C	K	3-Terminal Metal Can	SGR137AK	TO-3	
			SGR137AK-EV*		
			SGR137K		
			SGR137K-EV*		
-55°C to 125°C	T	3-Terminal Metal Can	SGR137AT	TO-39	
			SGR137AT-EV*		
			SGR137T		
			SGR137T-EV*		
-55°C to 125°C	IG	3-Pin Hermetic To-257	SGR137AIG	TO-257 (Isolated)	
			SGR137AIG-EV*		
			SGR137IG		
			SGR137IG-EV*		

\* EV is Microsemi's "Equivalent V" flow that follows MIL-PRF-38535 requirements for Class V processing.

## Connection Diagrams and Ordering Information

Ambient Temperature	Type	Package	Part Number	Packaging Type	Connection Diagram
-55°C to 125°C	L	20-Pin CERAMIC	SGR137AL	Ceramic (LCC) Leadless Chip Carrier	 <p><b>L PACKAGE</b> (Top View) PbSn Lead Finish</p> <p>* Both V<sub>OUT</sub> pins must be externally connected together at the device terminals.</p>
			SGR137AL-EV*		
			SGR137L		
			SGR137L-EV*		
<p><i>Notes:</i> All parts are viewed from the top.</p>					

\* EV is Microsemi's "Equivalent V" flow that follows MIL-PRF-38535 requirements for Class V processing.

## Absolute Maximum Ratings<sup>1</sup>

Parameter	Value	Units
Power Dissipation	Internally Limited	-
Input to Output Voltage Differential	40	V
Storage Temperature Range	-65 to 150	°C
Operating Junction Temperature	150	°C
Lead Temperature (Soldering, 10 Seconds)	300	°C

*Notes:*

1. Stresses above those listed in "ABSOLUTE MAXIMUM RATINGS", may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

## Thermal Data

Parameter	Value	Units
<b>K Package:</b>		
Thermal Resistance-Junction to Leads, $\theta_{JC}$	3.0	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	35	°C/W
<b>T Package:</b>		
Thermal Resistance-Junction to Leads, $\theta_{JC}$	15	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	120	°C/W
<b>IG Package:</b>		
Thermal Resistance-Junction to Leads, $\theta_{JC}$	3.5	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	42	°C/W
<b>L Package:</b>		
Thermal Resistance-Junction to Leads, $\theta_{JC}$	35	°C/W
Thermal Resistance-Junction to Ambient, $\theta_{JA}$	120	°C/W

*Notes:*

- Junction Temperature Calculation:  $T_J = T_A + (P_D \times \theta_{JA})$ .
- The above numbers for  $\theta_{JC}$  are maximums for limiting the thermal resistance of the package in a standard mounting configuration. The  $\theta_{JA}$  numbers are the guidelines for the thermal performance of the device/pcboard system. All of the above assume no ambient airflow.

## Recommended Operating Conditions<sup>2-3</sup>

Symbol	Parameter	Recommended Operating Conditions			Units
		Min	Typ	Max	
$V_{OUT}$	Input Voltage Range	-( $ V_{OUT}  + 3.5V$ )			V
<b>Operating Junction Temperature Range</b>					
	SGR137A/SGR137	-55		150	°C

*Note:*

2. Range over which the device is functional.
3. These ratings are applicable for junction temperatures of less than 135°C.

## Electrical Characteristics

Unless otherwise specified, these specifications apply over full operating ambient temperatures for SGR137A/SGR137 with  $-55^{\circ}\text{C} \leq T_J \leq 150^{\circ}\text{C}$ ,  $|V_{IN} - V_{OUT}| = 5.0\text{V}$ , and for  $I_{OUT} = 500\text{mA}$  (K and IG power packages), and  $I_{OUT} = 100\text{mA}$  (T and L packages). Although power dissipation is internally limited, these specifications are applicable for power dissipations of 2W for the T and L packages, and 20W for the K and IG packages.  $I_{MAX}$  is 1.5A for the K and IG packages and 0.5A for the T and L packages. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.

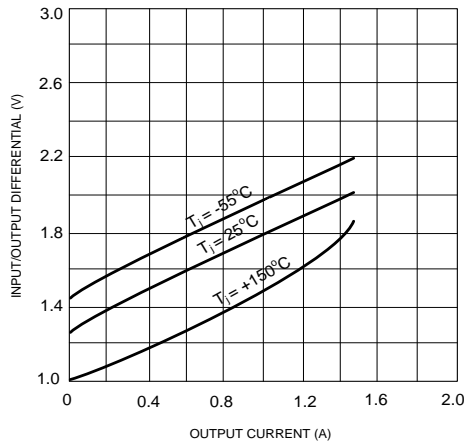
Symbol	Test Conditions	SGR137A			SGR137			Units
		Min.	Typ.	Max	Min.	Typ.	Max	
Reference Voltage <sup>6</sup>	$I_{OUT} = 10\text{mA}$ , $T_J = 25^{\circ}\text{C}$	-1.238	-1.250	-1.262	-1.225	-1.250	-1.275	V
	$3\text{V} \leq  V_{IN} - V_{OUT}  \leq 40\text{V}$ , $10\text{mA} \leq I_{OUT} \leq I_{MAX}$	-1.220	-1.250	-1.280	-1.200	-1.250	-1.300	V
Line Regulation <sup>4,6</sup>	$3\text{V} \leq  V_{IN} - V_{OUT}  \leq 40\text{V}$ , $I_{OUT} \leq I_{MAX}$							
	$T_J = 25^{\circ}\text{C}$		0.005	0.01		0.01	0.02	%/V
Load Regulation <sup>4</sup>	$10\text{mA} \leq I_{OUT} \leq I_{MAX}$							
	$ V_{OUT}  \leq 5\text{V}$ , $T_J = 25^{\circ}\text{C}$		5	25		15	25	mV
	$ V_{OUT}  \geq 5\text{V}$ , $T_J = 25^{\circ}\text{C}$		0.1	0.5		0.3	0.5	%
	$ V_{OUT}  \leq 5\text{V}$		10	50		20	50	mV
	$ V_{OUT}  \geq 5\text{V}$		0.2	1		0.3	1	%
Thermal Regulation <sup>5</sup>	$T_J = 25^{\circ}\text{C}$ , 10ms pulse		0.002	0.02		0.002	0.02	%/W
Ripple Rejection	$V_{OUT} = -10\text{V}$ , $f = 120\text{Hz}$							
	$C_{ADJ} = 0$ , $T_J = 25^{\circ}\text{C}$	60	66			60		dB
	$C_{ADJ} = 10\mu\text{F}$	70	80		66	77		dB
Adjust Pin Current	$T_A = 25^{\circ}\text{C}$		65	100		65	100	$\mu\text{A}$
Adjust Pin Current Change <sup>6</sup>	$3\text{V} \leq  V_{IN} - V_{OUT}  \leq 40\text{V}$		1.0	5		2	5	$\mu\text{A}$
	$10\text{mA} \leq I_{OUT} \leq I_{MAX}$		0.2	2		0.5	5	$\mu\text{A}$
Minimum Load Current	$ V_{IN} - V_{OUT}  \leq 40\text{V}$		2.5	5.0		2.5	5.0	mA
	$ V_{IN} - V_{OUT}  \leq 10\text{V}$		1.2	3		1.2	3.0	mA
Current Limit	$ V_{IN} - V_{OUT}  \leq 15\text{V}$							
	K, IG Packages	1.5	2.2	3.2	1.5	2.2		A
	T, L, Packages	0.5	0.8	1.5	0.5	0.8		A

Symbol	Test Conditions	SGR137A			SGR137			Units
		Min.	Typ.	Max	Min.	Typ.	Max	
Current Limit	$ V_{IN} - V_{OUT}  \leq 40V, T_J = 25^\circ C$							
	K, IG Packages	0.24	0.4	1.0	0.24	0.4		A
	T, L, Packages	0.15	0.25	0.5	0.15	0.25		A
Temperature Stability <sup>5</sup>			0.6	1.5		0.6		%
Long Term Stability <sup>5</sup>	$T_J = 125^\circ C, 1000 \text{ Hours}$		0.3	1		0.3	1	%
RMS Output Noise (% of $V_{OUT}$ )	$T_J = 25^\circ C, 10Hz \leq f \leq 10kHz^5$		0.003			0.003		%

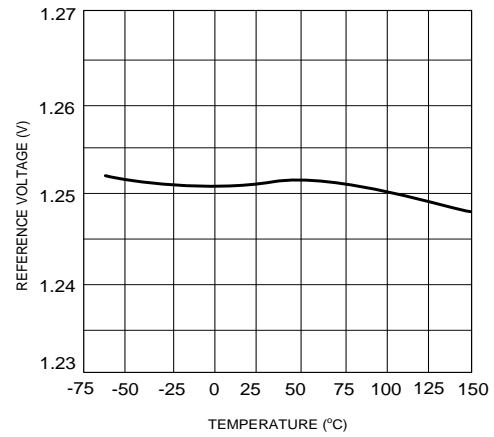
*Notes:*

- Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specification for thermal regulation.
- These parameters, although guaranteed, are not tested in production
- $I_{MAX}$  for K, and IG packages is  $V_{IN} - V_{OUT} = 3V / 1.5A$  and  $V_{IN} - V_{OUT} = 40V / 240mA$ . For T and L packages  $I_{MAX}$  is  $V_{IN} - V_{OUT} = 3V / 500mA$  and  $V_{IN} - V_{OUT} = 40V / 150mA$ .

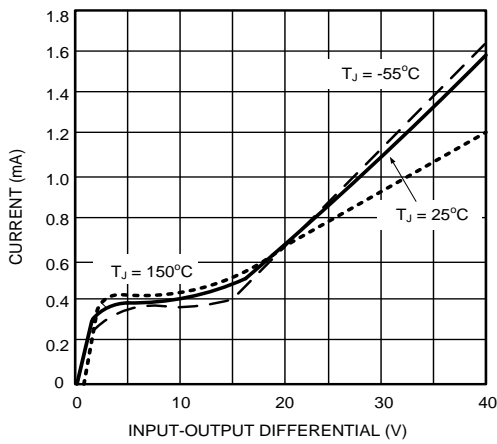
# Characteristic Curves



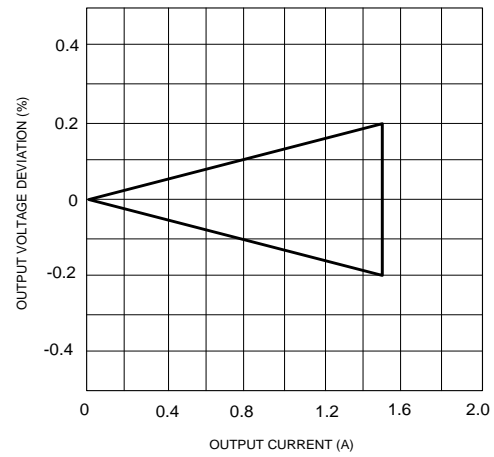
**Figure 3** - Input/Output Differential vs. Output Current



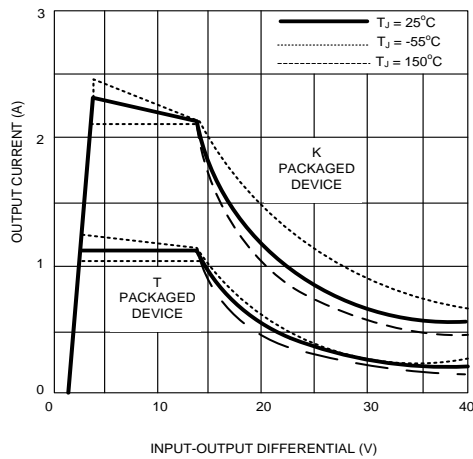
**Figure 4** - Reference Voltage Vs. Temperature



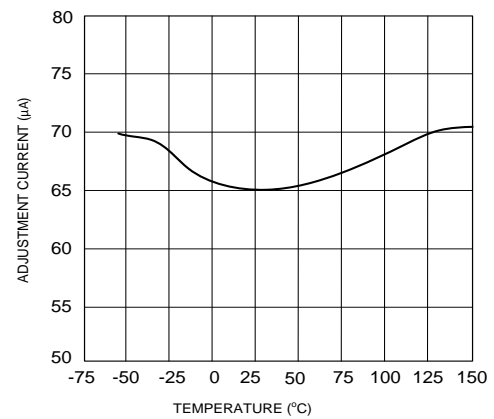
**Figure 5** - Current Vs. Input/Output Differential



**Figure 6** - Output Voltage Deviation Vs. Output Current\*



**Figure 7** - Input/Output Differential Vs. Output Current



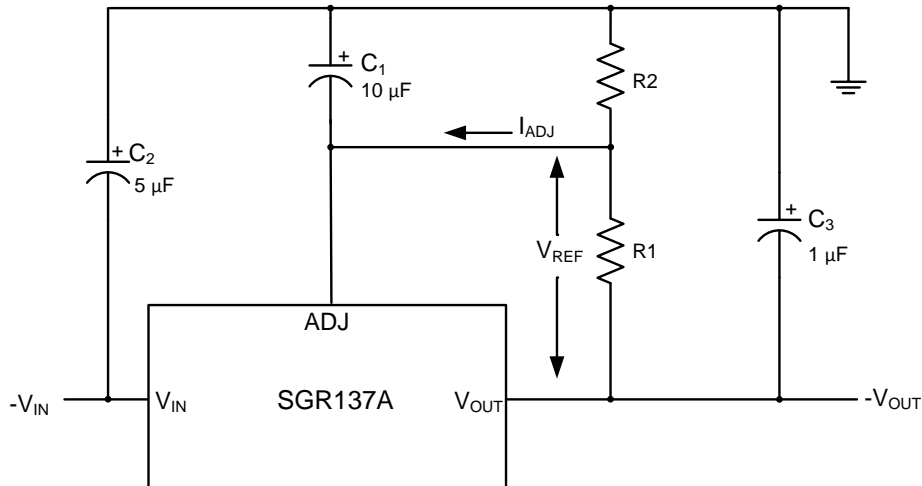
**Figure 8** - Adjustment Current Vs. Temperature

*Notes: \*The SGR137A has load regulation compensation which makes the typical unit read close to zero. This band represents the typical production spread.*

## Application Information

### Output Voltage

The output voltage is determined by two external resistors,  $R_1$  and  $R_2$



**Figure 9** - Output Voltage

The exact formula for the output voltage is:

$$V_{OUT} = V_{REF} \left( \frac{R_2 + R_1}{R_1} \right) + I_{ADJ} (R_2)$$

Where:  $V_{REF}$  = Reference Voltage and  $I_{ADJ}$  = Adjustment Pin Current. In most applications, the second term is small enough to be ignored, typically about 0.5% of  $V_{OUT}$ . In more critical applications, the exact formula should be used, with  $I_{ADJ}$  equal to 65  $\mu$ A. Solving for  $R_2$  yields:

$$R_2 = \frac{V_{OUT} - V_{REF}}{\frac{V_{REF}}{R_1} + I_{ADJ}}$$

Smaller values of  $R_1$  and  $R_2$  reduce the influence of  $I_{ADJ}$  on the output voltage, but the no-load current drain on the regulator is increased. Typical values for  $R_1$  are between 100  $\Omega$  and 300  $\Omega$ , giving 12.5mA and 4.2mA no-load current. There is an additional consideration in selecting  $R_1$  the minimum load current specification of the regulator. The operating current of the SGR137A flows from input to output. If this current is not absorbed by the load, the output of the regulator rises above the regulated value. The current drawn by  $R_1$  and  $R_2$  is normally high enough to absorb the current, but care must be taken in no-load situations where  $R_1$  and  $R_2$  have high values. The maximum value for the operating current, which must be absorbed, is 5mA for the SGR137A. If input and output voltage differential is less than 10V, the operating current that must be absorbed drops to 3mA.

Examples:

1. A precision 10V regulator to supply up to 1 Amp load current.
  - a. Select  $R_1 = 100\Omega$  to minimize effect of  $I_{ADJ}$
  - b. Calculate  $R_2 = \frac{V_{OUT} - V_{REF}}{\frac{V_{REF}}{R_1} + I_{ADJ}} = \frac{10V - 1.25V}{(1.25V/100\text{ ohms}) + 65\mu A} = 704\text{ ohms}$

A 15 V regulator to run off batteries and supply 50mA.  $V_{IN\ MAX} = 25V$

- c. To minimize battery drain, select  $R_1$  as high as possible

$$R_1 = \frac{1.25V}{3mA} = 417\Omega, \text{ use } 404\Omega, 1\%$$



## Typical Application Circuits

The output stability, load regulation, line regulation, thermal regulation, temperature drift, long term drift, and noise can be improved by a factor of 6.6 over the standard regulator configuration. This assumes a zener whose drift and noise is considerably better than the regulator itself. The LM329B has 20PPM/°C maximum drift and about 10 times lower noise than the regulator.

In the application as shown figure 10, regulators #2 to #N tracks regulator #1 to within  $\pm 24$  mV initially, and to  $\pm 60$  mV over all load, line, and temperature conditions. If any regulator output is shorted to ground, all other outputs drop to -2V. Load regulation of regulators #2 to #N are improved by  $V_{OUT}/1.25$  V compared to a standard regulator, so regulator #1 should be the one which has the lowest load current.

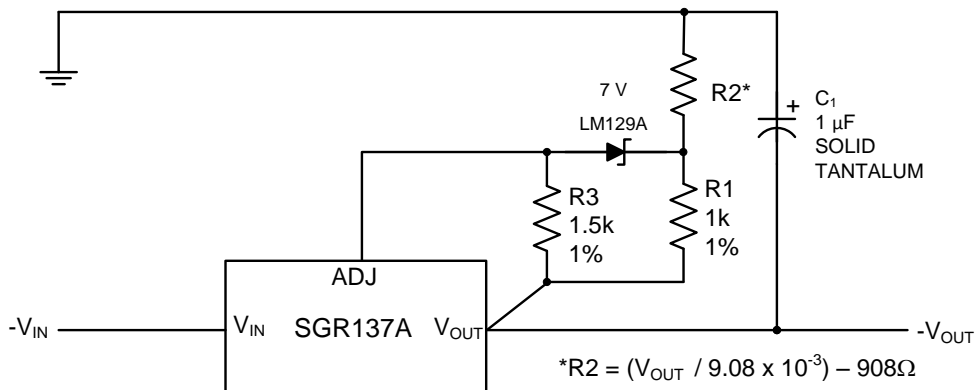


Figure 10 - High Stability Regulator

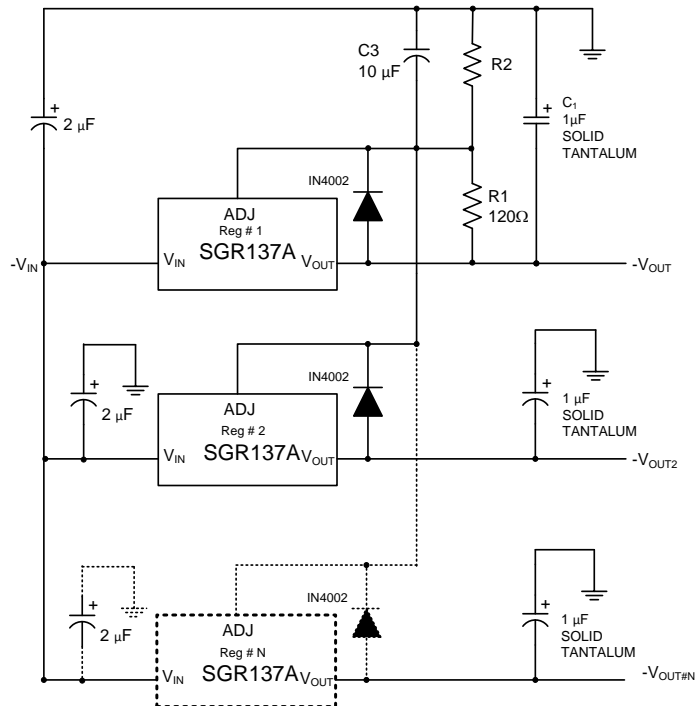
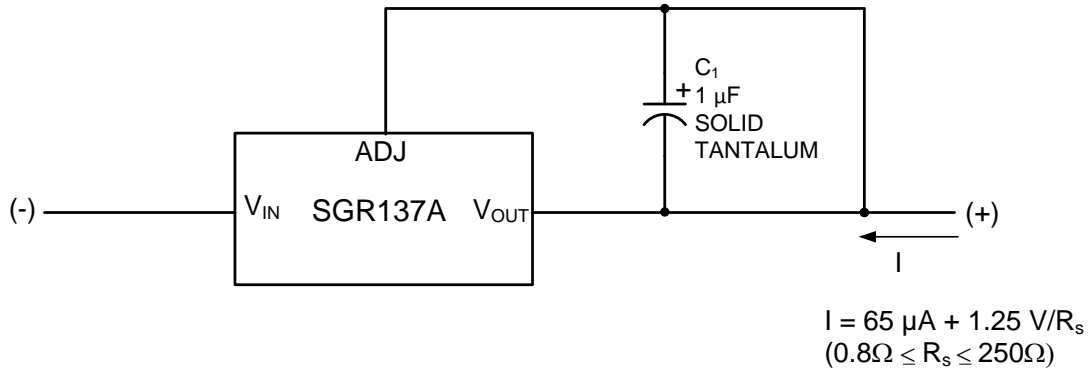
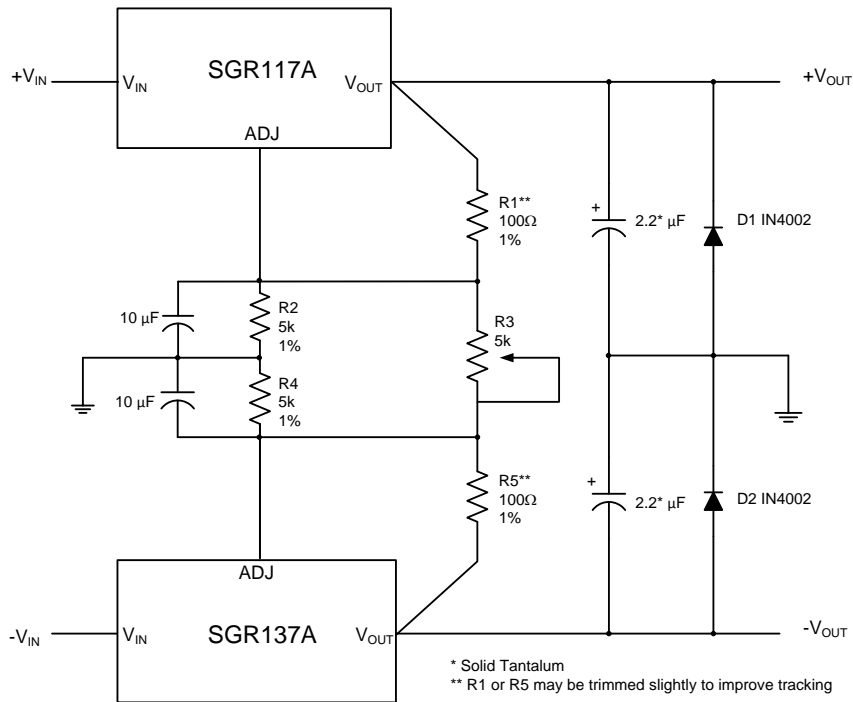


Figure 11 - Multiple Tracking Regulators



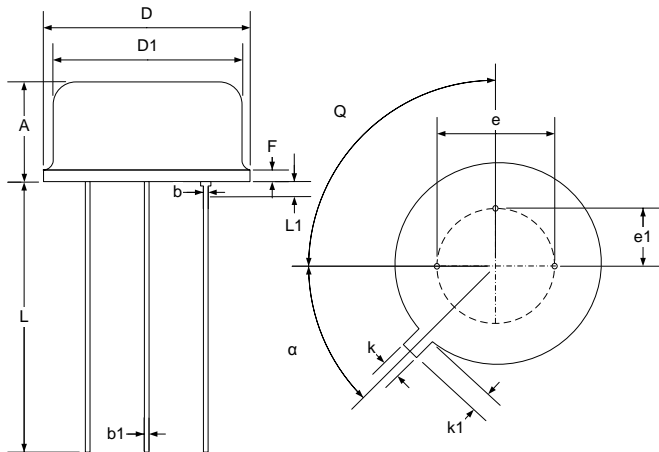
**Figure 12** - Current Regulator



**Figure 13** - Dual Tracking Supply  $\pm 1.25 \text{ V}$  To  $\pm 20 \text{ V}$

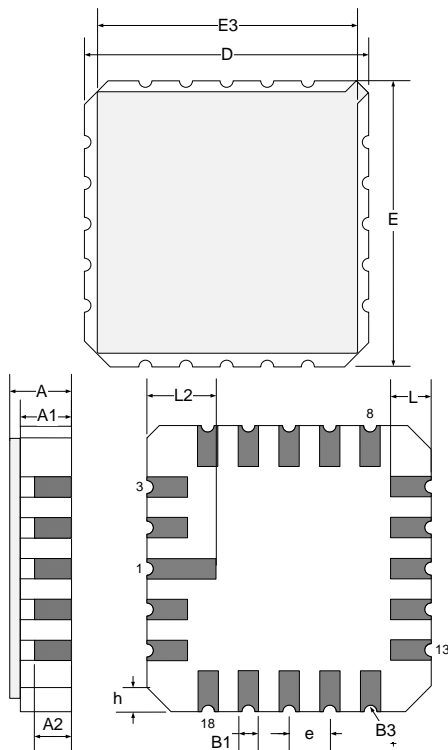
# Package Outline Dimensions

Controlling dimensions are in inches, metric equivalents are shown for general information.



Dim	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
D	8.89	9.40	0.350	0.370
D1	8.13	8.51	0.320	0.335
A	4.19	4.70	0.165	0.185
b	0.41	0.48	0.016	0.019
F	-	1.02	-	0.040
e	5.08 BSC		0.200 BSC	
k	0.71	0.86	0.028	0.034
k1	0.74	1.14	0.029	0.045
L	12.70	14.48	0.500	0.570
α	45° TYP		45° TYP	
e1	2.54 TYP		0.100 TYP	
b1	0.41	0.53	0.016	0.021
Q	90° TYP		90° TYP	
L1	-	1.27	-	0.50

Figure 14 - T 3-Pin Metal Can TO-39 Package Dimensions



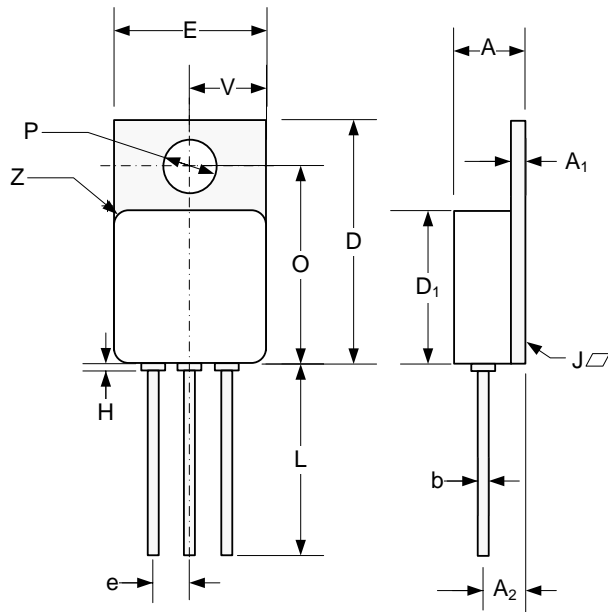
Dim	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
D/E	8.64	9.14	0.340	0.360
E3	-	8.128	-	0.320
e	1.270 BSC		0.050 BSC	
B1	0.635 TYP		0.025 TYP	
L	1.02	1.52	0.040	0.060
A	1.626	2.286	0.064	0.090
h	1.016 TYP		0.040 TYP	
A1	1.372	1.68	0.054	0.066
A2	-	1.168	-	0.046
L2	1.91	2.41	0.075	0.95
B3	0.203R		0.008R	

**Note:**

- All exposed metalized area shall be gold plated 60 micro-inch minimum thickness over nickel plated unless otherwise specified in purchase order.

Figure 15 - L 20-Pin Ceramic Leadless Chip Carrier (LCC) Package Dimensions

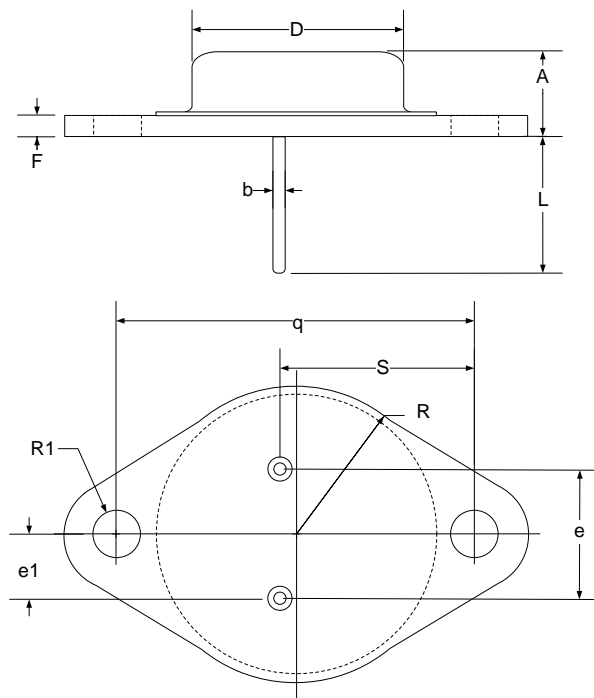
## Package Outline Dimensions



Dim	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.70	5.21	0.185	0.205
A1	0.89	1.14	0.035	0.045
A2	2.92	3.18	0.115	0.125
b	0.71	.081	0.027	0.032
D	16.38	16.76	0.645	0.660
D1*	10.41	10.92	0.410	0.430
e	2.54 BSC		0.100 BSC	
E*	10.41	10.67	0.410	0.420
H		0.50		0.020
L	12.70		0.500	
O	13.39	13.64	0.527	0.537
P	3.56	3.81	0.140	0.150
J		0.10		0.004
V	5.13	5.38	0.202	0.212
Z	1.40 TYP		0.055 TYP	

\*Excludes Weld Fillet Around Lid.

Figure 16 - G/G 3-Pin Hermetic TO-257 Package Dimensions



Dim	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	6.86	7.62	0.270	0.300
q	29.90	30.40	1.177	1.197
b	0.97	1.09	0.038	0.043
D	19.43	19.68	0.765	0.775
S	16.64	17.14	0.655	0.675
e	10.67	11.18	0.420	0.440
E1	5.21	5.72	0.205	0.225
F	1.52	2.03	0.060	0.080
R1	3.84	4.09	0.151	0.161
L	10.79	12.19	0.425	0.480
R	12.57	13.34	0.495	0.525

Figure 17 - K 3-Pin TO-3 Package Dimension



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